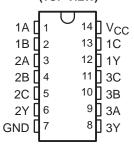
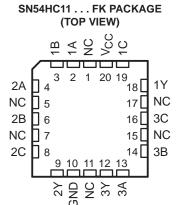
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I<sub>CC</sub>

SN54HC11 . . . J OR W PACKAGE SN74HC11 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t<sub>pd</sub> = 8 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max



NC - No internal connection

## description/ordering information

The 'HC11 devices contain three independent 3-input AND gates. They perform the Boolean function  $Y = A \bullet B \bullet C$  or  $Y = \overline{\overline{A} + \overline{B} + \overline{C}}$  in positive logic.

## **ORDERING INFORMATION**

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC11N	SN74HC11N
		Tube of 50	SN74HC11D	
	SOIC - D	Reel of 2500	SN74HC11DR	HC11
		Reel of 250	SN74HC11DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC11NSR	HC11
	SSOP – DB	Reel of 2000	SN74HC11DBR	HC11
		Tube of 90	SN74HC11PW	
	TSSOP - PW	Reel of 2000	SN74HC11PWR	HC11
		Reel of 250	SN74HC11PWT	
	CDIP – J	Tube of 25	SNJ54HC11J	SNJ54HC11J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC11W	SNJ54HC11W
<u> </u>	LCCC - FK	Tube of 55	SNJ54HC11FK	SNJ54HC11FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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# FUNCTION TABLE (each gate)

	INPUTS	OUTPUT	
Α	В	С	Y
Н	Н	Н	Н
L	X	Χ	L
Х	L	Χ	L
Х	X	L	L

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	e Note 1);) (see Note 1)	±20 mA ±20 mA ±25 mA ±50 mA 86°C/W
	N package	
	NS package	
	PW package	113°C/W
Storage temperature range, T <sub>Stg</sub>		−65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



## recommended operating conditions (see Note 3)

			S	N54HC1	ı	SI	N74HC1	1		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		2	5	6	2	5	6	V	
		V <sub>CC</sub> = 2 V	1.5			1.5				
VIH	VIH High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V	
		V <sub>CC</sub> = 6 V	4.2			4.2				
		V <sub>CC</sub> = 2 V			0.5			0.5	V	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35		
		VCC = 6 V			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
VO	Output voltage		0		VCC	0		VCC	V	
		V <sub>CC</sub> = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns	
		VCC = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			Т	A = 25°C	;	SN54l	HC11	SN74HC11			
PARAMETER	TEST CONDITIONS		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
V <sub>OH</sub> V <sub>I</sub> = 1		$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VoL	$V_I = V_{IH}$ or $V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			2		40		20	μΑ
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF

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# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER FROM		ТО	,,	T <sub>A</sub> = 25°C			SN54HC11		SN74HC11		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		35	100		150		125		
t <sub>pd</sub>	<sup>t</sup> pd A, B, or C	Υ	4.5 V		10	20		30		25	ns
			6 V		8	17		25		21	
		Y	2 V		25	75		110		95	
t <sub>t</sub>			4.5 V		7	15		22		19	ns
			6 V		5	13		19		16	

## operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	No load	25	pF

#### PARAMETER MEASUREMENT INFORMATION ٧cc From Output Input 50% 50% **Under Test Point** 0 V $C_L = 50 pF$ tPHL tPLH -(see Note A) Vон In-Phase 90% 90% 50% Output **LOAD CIRCUIT** 10% - tPHL tpi H - VCC Input 90% **Out-of-Phase** 50% 10% -Output Vol **VOLTAGE WAVEFORM VOLTAGE WAVEFORMS INPUT RISE AND FALL TIMES** PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_Q = 50 \Omega$ ,  $t_f = 6$  ns,  $t_f = 6$  ns.
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms



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## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-8404801VCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8404801VDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
84048012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8404801CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8404801DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/65204BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54HC11J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC11D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11DTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC11NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC11NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM



### PACKAGE OPTION ADDENDUM

9-Oct-2007

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74HC11PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC11PWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC11FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC11J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54HC11W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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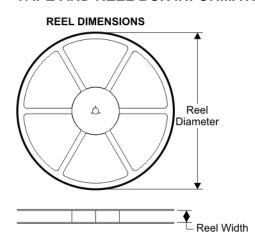
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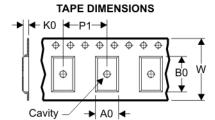




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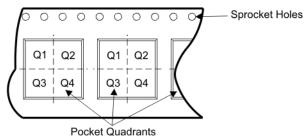
## TAPE AND REEL BOX INFORMATION





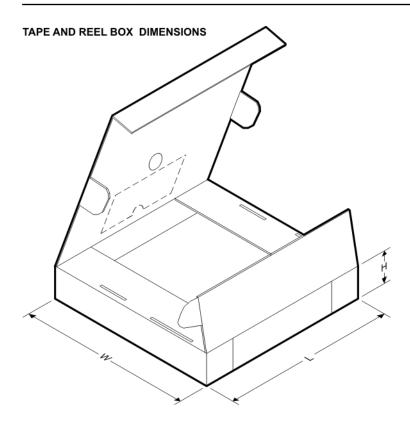
	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC11DBR	DB	14	SITE 41	330	16	8.2	6.6	2.5	12	16	Q1
SN74HC11DR	D	14	SITE 27	330	16	6.5	9.0	2.1	8	16	Q1
SN74HC11DR	D	14	SITE 41	330	16	6.5	9.0	2.1	8	16	Q1
SN74HC11NSR	NS	14	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1
SN74HC11PWR	PW	14	SITE 41	330	12	7.0	5.6	1.6	8	12	Q1





Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74HC11DBR	DB	14	SITE 41	346.0	346.0	33.0
SN74HC11DR	D	14	SITE 27	342.9	336.6	28.58
SN74HC11DR	D	14	SITE 41	346.0	346.0	33.0
SN74HC11NSR	NS	14	SITE 41	346.0	346.0	33.0
SN74HC11PWR	PW	14	SITE 41	346.0	346.0	29.0

## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

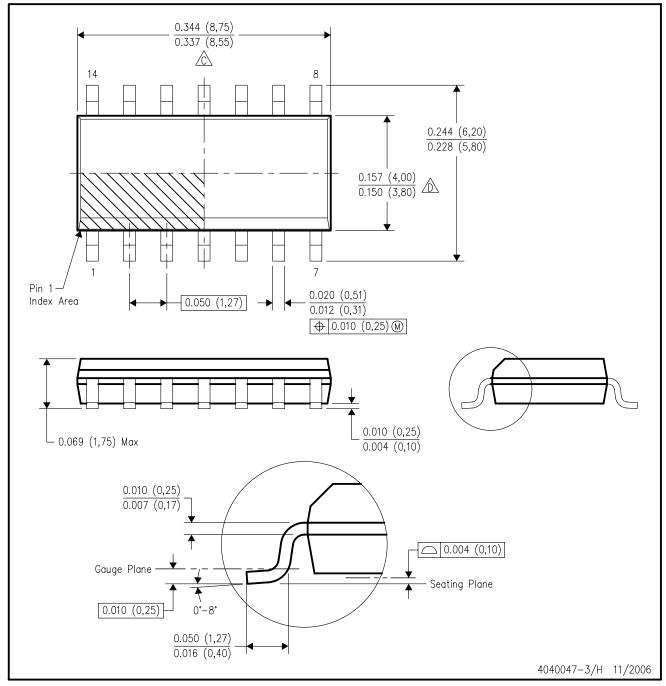


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153